

Product Category: Personal Computers

Marketing Name / Model [List multiple models if applicable.]

Name / Model #1: HP Compaq dx7400 Small Form Factor Business PC

Name / Model #2

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3 (1 sys board, 2 P/S PCAs
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		7
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Phillips screwdriver	
Description #2 Dikes	
Description #3 Torx screwdriver	T-15
3.0 Product Disassembly Process	

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- 1. To remove the access panel (see Figure 1):
 - a. Remove the two screws that secure the access panel to the computer chassis (1).
 - b. Slide the access panel back about 1.3 cm (1/2 inch), then lift it away from and off the unit (2).
- 1 Remove or cut all expansion cards, cables, and any other devices from the system board.
 - 3. To remove the power supply:
 - a. Remove the front bezel (see Figure 2).
 - b. Rotate the drive cage to its upright position.
 - c. Loosen the plastic cable fastener (Figure 3) and smaller plastic fastener.
 - d. Unplug all power supply wires from the system board.
 - e. Remove the three screws that secure the power supply to the back of the chassis (1).
- a. Remove the one screw in front of the power supply that secures the power supply to the chassis base (1).
 - g. Remove the serial port wire from on top of the power supply.

b. Slide the power supply about 1/2-inch (13 mm) toward the front of the chassis (2), rotate the power supply toward the heatsink so it clears the lip at the top of the chassis (3), and then lift the power supply out of the chassis (4) (see Figure 4).

2 To remove the battery: Locate the battery and battery holder on the system board. Depending on the type of battery holder on the system board, complete the following instructions to remove the battery. TYPE 1 BATTERY HOLDER (see Figure 5): Lift the battery out of the holder. TYPE 2 BATTERY HOLDER (see Figure 6): To release the battery from its holder, squeeze the metal clamp that extends above one edge of the battery. When the battery pops up, lift it out. TYPE 3 BATTERY HOLDER (see Figure 7): Pull back on the clip that holds the battery in place, and then remove the battery.

- 5. To remove the system board:
- a. Loosen the plastic cable fastener.

b. Remove the heatsink from the system board by loosening the four captive screws that secure the heatsink to the system board, and then lifting the heatsink from the system board.

c. Remove the eight screws that secure the system board to the chassis (1), slide the board about 13 cm (1/2 inch) toward the front of the chassis (2), and then lift the board out of the chassis (3). (see Figure 8).

- 6. Disassemble and remove required power supply components:
- a. Using dikes, cut the plastic clamp that secures the wires to the power supply cover.

b. Using a phillips screwdriver, remove the four screws that secure the cover to the power supply chassis

(see Figure 9).

NOTE: You do not need to remove the screws from the fan guard or the power connector.

c. Lift the cover off the power supply. You may need a flat blade screwdriver to loosen the cover prior to removing.

d. Using dikes, cut all cables connected to the PCA in the power supply.

e. To remove the large power supply PCA, remove the two screws from the inside, and the one screw from the outside that secure the power supply PCA to the chassis (see Figures 10 & 11).

f. Remove the power supply PCA from the power supply chassis.

g. Cut the small PCA from the large power supply PCA (see Figure 12).

h. Cut 7 capacitors from the PCA, as shown in Figure 12.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).







